



2829

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

Michitaka Urushima

Serial No.: 09/839,298

Group Art Unit: 2829

#6/Amend A  
8/24/02

Filed: April 23, 2001

Examiner: Geyer, Scott B.

C. Purvis

For: SEMICONDUCTOR DEVICE AND MANUFACTURING METHOD OF THE SAME

Honorable Commissioner of Patents  
Washington, D.C. 20231AMENDMENT UNDER 37 C.F.R. §1.111

Sir:

In response to the Office Action dated May 9, 2002, please amend the above-identified application as follows:

IN THE CLAIMS:

Please cancel claims 10-24 without prejudice or disclaimer.

Please amend claims 2, 5 and 7-9 as follows:

2. (Amended) the semiconductor device according to claim 1, further comprising:  
an interposer bonded through thermocompression bonding.

5. (Amended) A semiconductor device comprising:  
a semiconductor chip;  
an adhesive layer formed on a surface of said semiconductor chip on which an electrode is formed;

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